

# **Reliability Qualification Report**

for

**DDR4 SDRAM with Pb/Halogen Free  
(Industrial)**

**(256M×16, 25nm SDRAM AS4C256M16D4)**

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Test Item	Reference Standard	A/R Criteria	Failure/S.S.	Status	Failure Mode
Moisture Sensitivity	J-STD-020	0/1	0/228	PASS	N/A
HTST	JESD22-A103	0/1	0/76	PASS	N/A
TCT*	JESD22-A104	0/1	0/76	PASS	N/A
PCT*	JESD22-A102	0/1	0/76	PASS	N/A
HAST*	JESD22-A110	0/1	0/76	PASS	N/A

\* Sampling from Moisture Sensitivity

**Table 4. Environmental Test Criteria and Result**

### 3.4. ESD Test

Electrical discharge into semiconductor product is one of the leading causes of device failure in the customer's manufacturing process. Alliance performs the ESD test to ensure that the performance of AS4C256M16D4 will not be degraded to an unacceptable level by exposure to a succession of electro-static discharge. The test methods and test results are shown in Table 5.

Test Item	Test Method				Result (F/S.S)
	Reference Standard	Test Condition	Criteria	Sample	
H.B.M.	JESD22-A114	R=1.5K $\Omega$ , C=100pF	$\geq \pm 2KV$	3ea	0/3
M.M.	JESD22-A115	R=0K $\Omega$ , C=200pF	$\geq \pm 200V$	3ea	0/3
C.D.M.	JESD22-C101	Non-Socket Mode	$\geq \pm 500V$	3ea	0/3

**Table 5. ESD Test Condition and Result**

### 3.5. Latch-Up Test

CMOS products can be prone to over-voltage exceeding the maximum device rating if the parasitic p-n-p-n SCRs (Silicon-controlled rectifier) are improperly biased. When the SCR turns on, it draws excessive current and causes products being damaged by thermal runaway. The Table 6 shows the latch-up test method and the test result of no failure.

Test Item	Test Method			Result (F/S.S)
	Reference Standard	Test Condition & Criteria	Sample	
Latch-Up	JESD78	$V_{tr (+)} \geq 1.5 * V_{cc}$ $V_{tr (-)} \leq -0.5 * V_{cc}$ $I_{tr (+)} \geq 100mA$ $I_{tr (-)} \leq -100mA$	6ea	0/6

**Table 6. Latch-Up test Condition and Result**

#### 4. CONCLUSION

Reliability test is to ensure the ability of a product in order to perform a required function under specific conditions for a certain period of time. Through those tests, the devices of potential failure can be screened out before shipping to the customer. At the same time, the test results are fed back to process, design and other related departments for improving product quality and reliability.

According to the life time test data, *the short-term 48Hrs failure rate (= the normal operation 0-1 year) of AS4C256M16D4 is equal to 0 DPM at  $T_a=55^{\circ}C$  and  $V_{cc}= 1.2V / V_{pp}= 2.5V$  with 60% confidence level AND the long-term 1000Hrs failure rate (= the normal operation 1-10 year) of AS4C256M16D4 is equal to 15 FIT at  $T_a=55^{\circ}C$  and  $V_{cc}= 1.2V / V_{pp}= 2.5V$  with 60% confidence level.* The results of environmental test, ESD test and latch-up test also ensure that AS4C256M16D4 is manufactured under a precise control of quality work by Alliance and its subcontractors. ***Thus, this experiment based on the Alliance reliability test standard for above test items can all pass.***

With the extensive research and development activities and the cooperation of all departments, Alliance continuously sets and maintains higher standard of quality and reliability to satisfy the future demand of its customers.